



(1.00 mm) .0394"(SEI) (1.27 mm) .050"(SIBF)

NE-PIECE INTERFACE

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEI or see www.samtec.com?SIBF

Insulator Material:

ITSUIALUT MATERIAI: SEI = Liquid Crystal Polymer SIBF = Black Liquid Crystal Polymer Contact Material: Phosphor Bronze

Phospnor Bruilze
Plating:
SEI = Au over
50 µ" (1.27 µm) Ni
SIBF = Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating:
SEI = 2.3 A per pin
(1 pin powered)
SIBF = 2.5 A per pin
(1 nin powered)

Sibr = 2.5 A per piri (1 pin powered)

Operating Temp Range:
-55 °C to +125 °C

Mating Force:
SEI = 50 g (0.49 N) per contact

Voltage Rating:
SEI = 250 VAC

SEI = 250 VAC SIBF = 155 VAC

Cycles: SEI = 100 min Contact Deflection: SEI = (0.46 mm) .018" nominal RoHS Compliant:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity (SEI): (0.10 mm) .004" max (05-25) (0.15 mm) .006" max (30)* *(.004" stencil solution may be available; contact IPG@samtec.com)

SMT Lead Coplanarity (SIBF): (0.10 mm) .004" max (05-20) (0.15 mm) .006" max (25)* *(.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



